

**CUSTOMIZED MESH PLANE, METHOD AND COMPUTER PROGRAM
PRODUCT FOR CREATING CUSTOMIZED MESH PLANES WITHIN
ELECTRONIC PACKAGES**

Field of the Invention

- 5 The present invention relates generally to the data processing field, and more particularly, relates to a customized mesh plane, method, and computer program product for creating customized mesh planes within electronic packages.

Description of the Related Art

- 10 Electronic packages typically include multiple layers or planes including multiple signal, voltage and ground planes. Some electronic packages utilize a mesh structure to construct what appears to be voltage or ground plane. The mesh structure is needed to allow enough non-metal area to insure proper joining or lamination of the plane structures.
- 15 When designing an electronic package that must utilize a mesh plane, such as, for a power plane or a ground plane, many times the adjacent signal traces may line up with holes in the mesh rather than on the mesh lines. In some cases the signal lines may not line up on the mesh lines due to its relative placement in the escape from the chip, or due to the signal line
- 20 is escaping diagonally across the mesh openings.

A signal line disposed above or below mesh holes in the mesh plane has a different characteristic impedance than a signal line disposed directly

above or below a mesh trace. Signal crosstalk also may occur to a greater extent through the mesh holes to signal traces disposed above or below the mesh holes.

5 A need exists for a mechanism for customizing the mesh plane for optimizing signal integrity and to meet all manufacturing limitations for an electronic package.

Summary of the Invention

10 A principal object of the present invention is to provide a customized mesh plane, method, and computer program product for creating customized mesh planes in electronic packages. Other important objects of the present invention are to provide such method, apparatus, and computer program product for creating customized mesh planes in electronic packages substantially without negative effect and that overcome many of the disadvantages of prior art arrangements.

15 In brief, a customized mesh plane, method, and computer program product are provided for creating customized mesh planes in electronic packages. Electronic package physical design data is received and signal traces in each adjacent plane to a mesh plane are compared with the mesh layout. Signal traces adjacent to mesh holes are identified. A fill method is
20 selected to modify the mesh layout to replace selected mesh holes with added mesh structure aligned with the identified signal traces.

In accordance with features of the invention, a plurality of predefined fill methods are provided. One of the multiple, predefined fill methods is selected to modify the mesh layout using predefined design rules or is
25 selected by a user. The added mesh structure aligned with the identified signal traces that is provided by one or a combination of the predefined fill methods includes one or a selected combination of a crosshair structure, a single line, a signal mirror, a mesh shifted structure, a complete fill structure, a metal fill structure, and a corner fill structure.

30 **Brief Description of the Drawings**

The present invention together with the above and other objects and advantages may best be understood from the following detailed description of the preferred embodiments of the invention illustrated in the drawings, wherein:

5 FIGS. 1A and 1B are block diagram representations illustrating a computer system and operating system for implementing methods for creating customized mesh planes within electronic packages in accordance with the preferred embodiment;

10 FIG. 2 is a flow chart illustrating exemplary sequential steps for creating a customized mesh plane in accordance with the preferred embodiment;

 FIG. 3 is a diagram illustrating an exemplary signal plane in an electronic package;

15 FIG. 4 is a diagram illustrating the exemplary signal plane of FIG. 3 together with an initial mesh plane in the electronic package;

 FIGS. 5, 6, 7, 8, 9, 10, and 11 illustrate the exemplary signal plane of FIG. 3 with alternative customized mesh planes created in accordance with fill methods of the preferred embodiment; and

20 FIG. 12 is a block diagram illustrating a computer program product in accordance with the preferred embodiment.

Detailed Description of the Preferred Embodiments

25 Referring now to the drawings, in FIGS. 1A and 1B there is shown a computer system generally designated by the reference character 100 for implementing methods for creating customized mesh planes within electronic packages in accordance with the preferred embodiment. Computer system 100 includes a main processor 102 or central processor unit (CPU) 102 coupled by a system bus 106 to a memory management unit (MMU) 108 and system memory including a dynamic random access memory (DRAM) 110, a nonvolatile random access memory (NVRAM) 112, and a flash

memory 114. A mass storage interface 116 coupled to the system bus 106 and MMU 108 connects a direct access storage device (DASD) 118 and a CD-ROM drive 120 to the main processor 102. Computer system 100 includes a display interface 122 coupled to the system bus 106 and
5 connected to a display 124.

Computer system 100 is shown in simplified form sufficient for understanding the present invention. The illustrated computer system 100 is not intended to imply architectural or functional limitations. The present invention can be used with various hardware implementations and systems
10 and various other internal hardware devices, for example, multiple main processors.

As shown in FIG. 1B, computer system 100 includes an operating system 130, an electronic package design program 132, a mesh plane-customizing program 134 of the preferred embodiment, and a user interface
15 136. A library including a plurality of fill methods 138, #1-N and manufacturing design limitation rules 140 are stored in accordance with the mesh plane customizing methods of the preferred embodiment. Fill methods 140 #1-N include, for example, a crosshair fill method, a single line fill method, a signal mirror fill method, a mesh shifting fill method, a complete fill
20 method, and a corner fill method that are used individually or in various combinations for creating customized mesh planes in accordance with the preferred embodiment.

Various commercially available computers can be used for computer system 100, for example, an IBM personal computer. CPU 102 is suitably
25 programmed by the mesh plane-customizing program 134 to execute the flowchart of FIG. 2 for creating customized mesh planes within electronic packages in accordance with the preferred embodiment.

In accordance with features of the preferred embodiment, a method is provided that receives a nearly completed physical package design, reads
30 the design data and calculates instructions to fill in mesh holes at instances which are adjacent to signal traces. Mesh structure or traces added to the mesh planes to fill the mesh holes include of a variety of different shapes depending upon manufacturing design limitation rules 140 that define how

much metal may be added to the mesh plane and what manufacturing shapes are acceptable. It should be understood that this method could be manually implemented by visually checking the design system, while the mesh plane-customizing program 134 of the preferred embodiment
5 advantageously is used to automate the mesh plane customizing process.

In accordance with features of the preferred embodiment, a customized mesh plane created by the mesh plane customizing method provides improved signal integrity resulting from a more consistent characteristic impedance and also provides improved signal isolation than
10 conventional mesh plane arrangements. The automated method for customizing the mesh plane of the preferred embodiment allows a designer to rapidly construct an electronic package design including customized mesh planes that meets all of the manufacturing limitations while optimizing for signal integrity.

Referring to FIG. 2, there are shown exemplary steps performed by the computer system 100 for implementing methods for creating customized mesh planes within electronic packages in accordance with the preferred embodiment starting at a block 200. Electronic package physical design data is loaded as indicated in a block 202. Signal traces in each adjacent
15 plane to a mesh plane are compared to the mesh plane layout as indicated in a block 204. Signal traces in each adjacent plane adjacent to mesh holes are identified as indicated in a block 206. A user optionally is queried for input, such as to query the user for one or more fill method selections, as indicated in a block 208. As indicated in a block 210, one or more fill
20 methods are selected from a library of fill methods 138 at block 212, and the mesh layout is modified using the selected fill method or methods to add mesh structure to fill selected mesh plane holes adjacent to identified signal traces. A customized mesh plane is created as indicated in a block 214.
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Referring now to FIGS. 3 and 4, in FIG. 3 an exemplary signal plane
30 in an electronic package is shown and generally designated by reference character 300. FIG. 4 illustrates the exemplary signal plane 300 together with an exemplary adjacent mesh plane generally designated by reference character 400. Mesh plane 400 illustrates a typical grid mesh plane defined by a plurality of uniformly spaced apart horizontal mesh traces 402 and a

plurality of uniformly spaced apart vertical mesh traces 404.

As shown in FIG. 4 signal plane 300 includes a pair of vertically
extending signal traces generally designated by reference character 302 and
a pair of diagonally extending signal traces generally designated by
5 reference character 304 that are disposed above or below mesh holes in the
mesh plane 400.

FIGS. 5, 6, 7, 8, 9, 10, and 11 illustrate alternative customized mesh
planes created in accordance the preferred embodiment using a single or a
combination of fill methods 140 #1-N for optimizing signal integrity and signal
10 isolation.

Referring now to FIG. 5, there is shown an exemplary customized
mesh plane generally designated by reference character 500 in accordance
a crosshair fill method of the preferred embodiment. Customized mesh
plane 500 includes a crosshair structure 502 added to the mesh plane 400
15 of FIG. 4 filling selected mesh plane holes adjacent to identified signal traces
302 and 304.

Referring now to FIG. 6, there is shown an exemplary customized
mesh plane generally designated by reference character 600 in accordance
a single line fill method and the crosshair fill method of the preferred
20 embodiment. Customized mesh plane 600 includes a single line structure
602 filling selected mesh plane holes adjacent to one identified signal trace
302 and the crosshair structure 502 added to the mesh plane 400 of FIG. 4
filling selected mesh plane holes adjacent to one identified signal trace 304.

Referring now to FIG. 7, there is shown an exemplary customized
25 mesh plane generally designated by reference character 700 in accordance
a signal mirror method of the preferred embodiment. Customized mesh
plane 700 includes a signal mirror structure 702 added to the mesh plane
400 of FIG. 4 that provides a substantially exact mirror of the signal plane
300. The signal plane 300 not shown in FIG. 7 is generally aligned with the
30 illustrated signal mirror structure 702.

Referring now to FIG. 8, there is shown an exemplary customized

mesh plane generally designated by reference character 800 in accordance
a shifted fill method of the preferred embodiment. Customized mesh plane
800 includes shifted mesh structure generally designated by reference
character 802 and rotated mesh structure generally designated by reference
5 character 804 filling selected mesh plane holes adjacent to identified signal
traces 302 and 304.

Referring now to FIG. 9, there is shown an exemplary customized
mesh plane generally designated by reference character 900 in accordance
a corner fill method and the single line fill method of the preferred
10 embodiment. Customized mesh plane 900 includes a corner fill structure
902 filling selected mesh plane holes adjacent to identified signal trace 304
and the single line structure 602 added to the mesh plane 400 of FIG. 4
filling selected mesh plane holes adjacent to one identified signal trace 302.

Referring now to FIG. 10, there is shown an exemplary customized
15 mesh plane generally designated by reference character 1000 in accordance
a complete fill method and the single line fill method of the preferred
embodiment. Customized mesh plane 1000 includes a complete fill
structure 1002 filling selected mesh plane holes adjacent to one identified
signal trace 304 and the single line structure 602 added to the mesh plane
20 400 of FIG. 4 filling selected mesh plane holes adjacent to one identified
signal trace 302.

Referring now to FIG. 11, there is shown an exemplary customized
mesh plane generally designated by reference character 1100 in accordance
an alternative shape fill method and the crosshair and single line fill methods
25 of the preferred embodiment. Customized mesh plane 1100 includes an
alternative shaped fill structure 1102 and the single line structure 602 filling
selected mesh plane holes adjacent to one identified signal trace 304 and
the crosshair structure 502 added to the mesh plane 400 of FIG. 4 filling
selected mesh plane holes adjacent to one identified signal trace 302.

30 Referring now to FIG. 12, an article of manufacture or a computer
program product 1200 of the invention is illustrated. The computer program
product 1200 includes a recording medium 1202, such as, a floppy disk, a
high capacity read only memory in the form of an optically read compact disk

or CD-ROM, a tape, a transmission type media such as a digital or analog communications link, or a similar computer program product. Recording medium 1202 stores program means 1204, 1206, 1208, 1210 on the medium 1202 for carrying out the methods for creating customized mesh
5 planes within electronic packages of the preferred embodiment in the computer system 100 of FIGS. 1A and 1B.

A sequence of program instructions or a logical assembly of one or more interrelated modules defined by the recorded program means 1204, 1206, 1208, 1210, direct the computer system 100 for creating customized
10 mesh planes of the preferred embodiment.

While the present invention has been described with reference to the details of the embodiments of the invention shown in the drawing, these details are not intended to limit the scope of the invention as claimed in the appended claims.